

**AZ809A** 

#### **General Description**

The AZ809A is a precision system supervisor and reset circuit designed to monitor the power supplies in microprocessor and digital system. It provides a reset signal to the host processor during power-up, power-down, and brownout conditions.

The AZ809A has an active-low RESET output, three standard reset options are offered to support 5V, 3.3V, and 3.0V system. Whenever the system supply voltage declines below the internal fixed reset threshold, the AZ809A asserts a reset signal and the reset signal remains asserted for 240ms after  $V_{CC}$  rises above the threshold.

The AZ809A has a push-pull output, no external components are required. The output is guaranteed to be in the correct state at  $V_{CC}$  level as low as 1V. The AZ809A is optimized to reject fast transient glitches on the VCC line. When the  $V_{CC}$  is 3.3V, the supply current consumption is about  $6\mu A$  typically.

The IC is available in SOT-23 package.

#### **Features**

- Precise Monitoring of 3.0V, 3.3V, and 5.0V Supply Voltages
- 140ms Minimum Reset Pulse Width
- Active-low RESET Output
- Push-Pull RESET Output
- No External Components
- Reset Valid Down to V<sub>CC</sub>=1.0V
- Power Supply Fast Transient Immunity
- Specified Over Full Temperature Range: -40 to 105°C

### **Applications**

- Microprocessor Systems
- Portable/Battery-Powered Systems
- Embedded Controllers
- Automotive
- Intelligent Instruments
- Wireless Communication Systems
- PDAs and Handheld Equipment
- Set-Top Boxes
- ADSL Modems

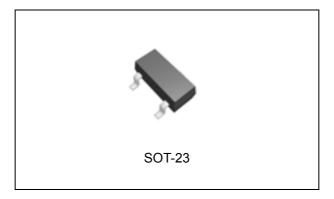


Figure 1. Package Type of AZ809A



**AZ809A** 

# **Pin Configuration**

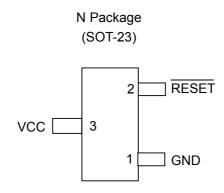


Figure 2. Pin Configuration of AZ809A (Top View)

# **Pin Description**

Pin Number	Pin Name	Function
1	GND	Ground pin
2	RESET	Active low output. The $\overline{RESET}$ is asserted LOW if $V_{CC}$ falls below the reset threshold and remains LOW for the 240ms typical reset timeout period (140ms minimum) after $V_{CC}$ exceeds the threshold
3	VCC	Power supply input voltage (3.0V, 3.3V, 5.0V)



**AZ809A** 

# **Functional Block Diagram**

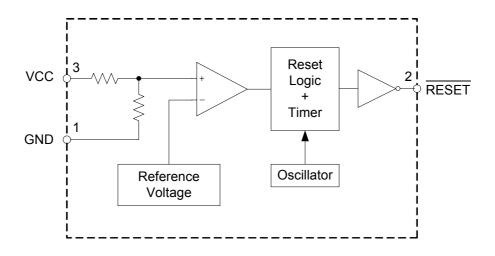
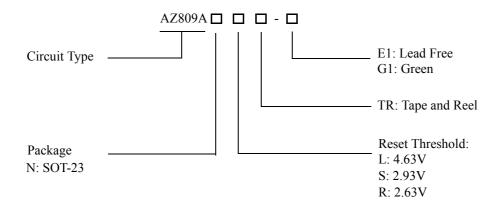


Figure 3. Functional Block Diagram of AZ809A

# **Ordering Information**



Package		Reset Part Number		lumber	ber Marki		Packing	
		Threshold	Lead Free	Green	Lead Free	Green	Type	
SOT-23	-40 to 105°C	4.63V	AZ809ANLTR-E1	AZ809ANLTR-G1	EH7	GH7	Tape & Reel	
		2.93V	AZ809ANSTR-E1	AZ809ANSTR-G1	EH1	GH1		
		2.63V	AZ809ANRTR-E1	AZ809ANRTR-G1	ЕН6	GH6		

BCD Semiconductor's Pb-free products, as designated with "E1" suffix in the part number, are RoHS compliant. Products with "G1" suffix are available in green package.

Oct. 2010 Rev. 1. 3

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**AZ809A** 

## **Absolute Maximum Ratings (Note 1)**

Parameter	Symbol	Value	Unit
Supply Voltage	V <sub>CC</sub>	-0.3 to 6	V
RESET		-0.3 to V <sub>CC</sub> +0.3	V
Input Current, VCC Pin		20	mA
Output Current, RESET Pin		20	mA
Rate of Rise, V <sub>CC</sub>		100	V/µs
Continuous Power Dissipation		320	mW
Junction Temperature	$T_{\mathrm{J}}$	150	°C
Storage Temperature	T <sub>STG</sub>	-65 to 150	°C
Lead Temperature (Soldering, 10sec)	$T_{LEAD}$	260	°C
ESD (Human Body Model)		6000	V
ESD (Machine Model)		400	V

Note 1: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

# **Recommended Operating Conditions**

Parameter	Symbol	Min	Max	Unit
Supply Voltage	$V_{CC}$	1	5.5	V
Operating Ambient Temperature Range	$T_{\mathbf{A}}$	-40	105	°C



**AZ809A** 

#### **Electrical Characteristics**

( $V_{CC}$  is over the full voltage range,  $T_A$ =-40°C to 105°C, unless otherwise noted.

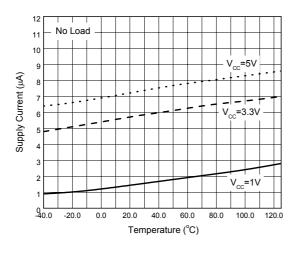
Typical values at  $T_A$ =25°C,  $V_{CC}$ =5V for L device,  $V_{CC}$ =3.3V for S device and  $V_{CC}$ =3V for R device.)(Note 2)

Parameter	Symbol	Conditions		Min	Тур	Max	Unit
Input Voltage (V <sub>CC</sub> ) Range	ut Voltage ( $V_{CC}$ ) Range $V_{CC}$ $T_A=0^{\circ}C$ to $85^{\circ}C$		1.0		5.5	V	
		$T_A$ =-40°C to 105°C		1.2		5.5	Ī , ,
	$I_{CC}$	L Devices	$T_A$ =-40°C to 85°C, $V_{CC}$ <5.5V		7	11	μА
Supply Current			$T_A$ =-40°C to 105°C, $V_{CC}$ <5.5V			12	
Supply Current		R/S Devices	$T_A$ =-40°C to 85°C, $V_{CC}$ <3.6V		6	10	
			$T_A$ =-40°C to 105°C, $V_{CC}$ <3.6V			11	
			T <sub>A</sub> =25°C	4.56	4.63	4.70	V
		L Devices	$T_{A}$ =-40°C to 85°C	4.50		4.75	
	$ m V_{TH}$		$T_A = -40^{\circ} \text{C to } 105^{\circ} \text{C}$	4.40		4.86	
		S Devices	$T_A=25^{\circ}C$	2.89	2.93	2.96	
Reset Threshold			$T_A$ =-40°C to 85°C	2.85		3.00	
			$T_A = -40^{\circ} \text{C to } 105^{\circ} \text{C}$	2.78		3.08	
		R Devices	T <sub>A</sub> =25°C	2.59	2.63	2.66	
			$T_A = -40^{\circ} \text{C to } 85^{\circ} \text{C}$	2.55		2.70	
			$T_A$ =-40°C to 105°C	2.50		2.76	
Reset Threshold Temperature Coefficient		T <sub>A</sub> =-40°C to 105°C			30		ppm/°C
VCC to Reset Delay		V <sub>CC</sub> =V <sub>TH</sub> to V <sub>TH</sub> -100mV			20		μs
Reset Active Timeout Period		$T_A = -40^{\circ} \text{C to}$	85°C	140	240	560	me
Reset Active Timeout Feriod		$T_{A}$ =-40°C to 105°C		100		840	ms
	ut Voltage V <sub>OL</sub>	R/S Devices V <sub>CC</sub> =V <sub>TH</sub> (min), I <sub>SINK</sub> =1.2mA			0.3		1
Low RESET Output Voltage		L Devices	V <sub>CC</sub> =V <sub>TH</sub> (min), I <sub>SINK</sub> =3.2mA		0.4		V
Down RESET Output Volunge		V <sub>CC</sub> >1.1V, I <sub>SINK</sub> =50μA			0.3		1
	age V <sub>OH</sub>	R/S Devices V <sub>CC</sub> >V <sub>TH</sub> (max), I <sub>SOURCE</sub> =500μA		0.8V <sub>CC</sub>			
High RESET Output Voltage		L Devices	V <sub>CC</sub> >V <sub>TH</sub> (max), I <sub>SOURCE</sub> =800μA	V <sub>CC</sub> - 1.5			V

Note 2. Production testing done at T<sub>A</sub>=25°C. Over temperature specifications guaranteed by design only.



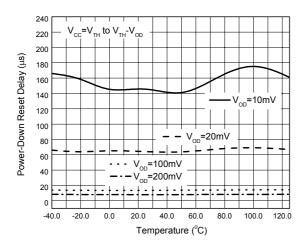
# **Typical Performance Characteristics**



340 Power-up Reset Timeout Period (ms) 320 300 280 240 220 -40.0 -20.0 0.0 20.0 60.0 80.0 100.0 40.0 Temperature (°C)

Figure 4. Supply Current vs. Temperature

Figure 5. Power-up Reset Timeout vs. Temperature



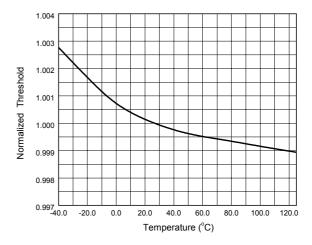


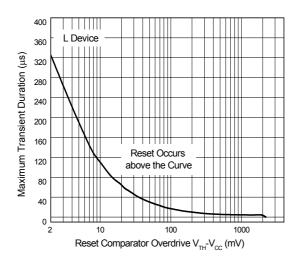
Figure 6. Power-down Reset Delay vs. Temperature

Figure 7. Normalized Reset Threshold vs. Temperature





## **Typical Performance Characteristics (Continued)**



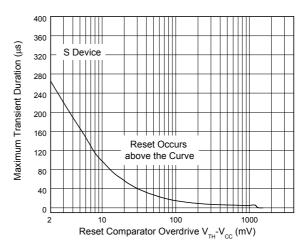


Figure 8. Maximum Transient Duration NOT Causing a Reset Pulse vs. Reset Comparator Overdrive

Figure 9. Maximum Transient Duration NOT Causing a Reset Pulse vs. Reset Comparator Overdrive

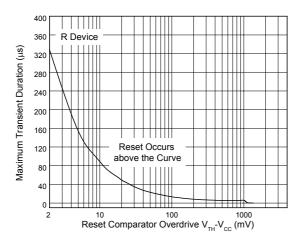
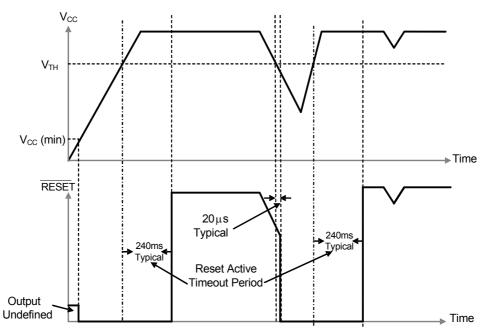


Figure 10. Maximum Transient Duration NOT Causing a Reset Pulse vs. Reset Comparator Overdrive



### **Operating Diagram**



The AZ809A asserts a reset signal LOW whenever the VCC supply voltage is below the threshold voltage and remains asserted for 240ms typically after the VCC has risen above the threshold.

Figure 11. Reset Timing Diagram of AZ809A

# **Application Information**

# Valid RESET with V<sub>CC</sub> under 1.0 V

The AZ809A  $\overline{\text{RESET}}$  output is valid to  $V_{\text{CC}}$ =1.0V. Below this voltage, the output becomes an open circuit and doesn't sink current. Therefore, high-impedance CMOS logic input connected to  $\overline{\text{RESET}}$  can drift to undetermined voltages.

To ensure that the AZ809A RESET is in a known state when  $V_{CC}$  is under 1.0V, a 100K $\Omega$  pull-down resistor between the RESET pin and GND is recommended to discharge stray capacitances and maintain the output low.

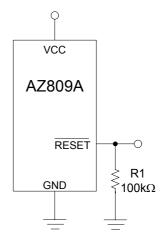


Figure 12.  $\overline{\text{RESET}}$  Valid to  $V_{\text{CC}}$ =0V

Oct. 2010 Rev. 1. 3

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#### **Application Information (Continued)**

#### **Negative Going V<sub>CC</sub> Transient**

The AZ809A is optimized to immune fast negative-going transients or glitches on the  $V_{CC}$  line, and the sensitivity depends on the duration of the transient and the magnitude of the undershoot below the reset threshold (reset comparator overdrive). Figure 13 shows the maximum pulse width of a negative-going  $V_{CC}$  transient that will not cause a reset pulse. As the magnitude of the transient increases (goes farther below the reset threshold), the maximum allowable pulse width decreases. Any combination of duration and overdrive that lies under the curve will not generate a reset signal, typically, a  $V_{CC}$  transient that goes 100 mV below the reset threshold and lasts about  $20 \mu \text{s}$  or less will not cause a reset pulse.

A  $0.1\mu F$  bypass capacitor mounted as close as possible to the  $V_{CC}$  pin will provide additional transient rejection.

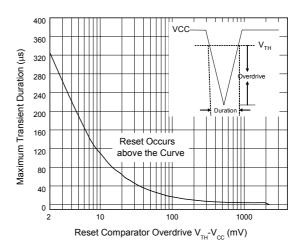


Figure 13. Maximum Transient Duration NOT Causing a Reset Pulse vs. Reset Comparator Overdrive

### **Typical Application**

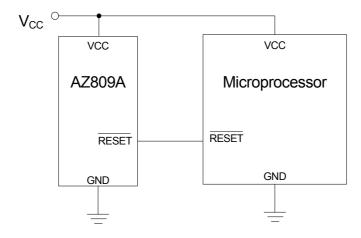


Figure 14. Typical Application of AZ809A

Oct. 2010 Rev. 1. 3

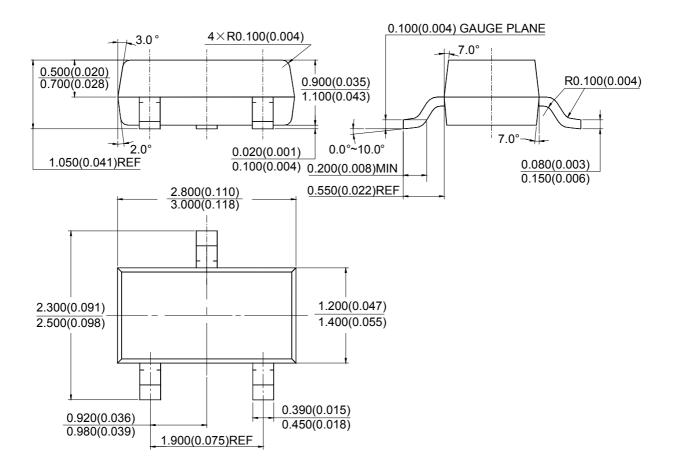
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#### **Mechanical Dimensions**

SOT-23 Unit: mm(inch)







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